

Features

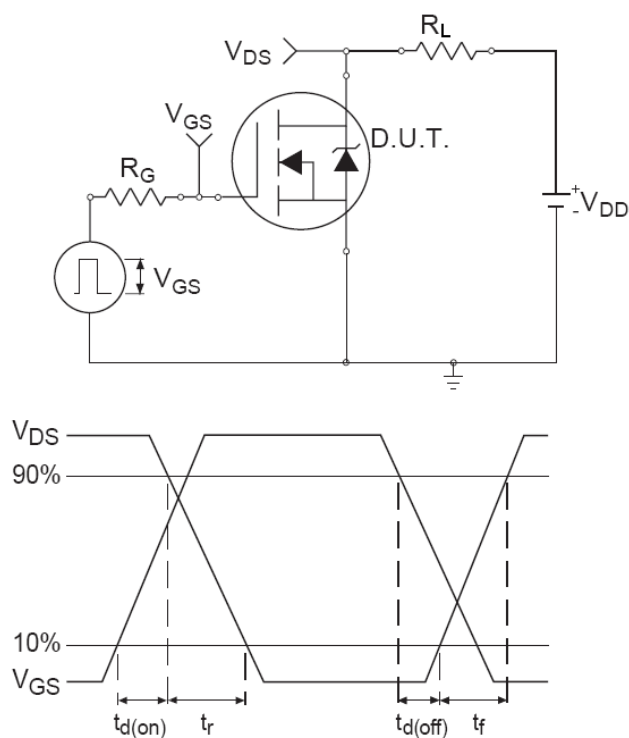
- V_{DSS}=200V/V_{GSS}=±25V/I_D=9A
R_{DS(ON)}=5mΩ(max.)@V_{GS}=10V
- Low Dense Cell Design
- Reliable and Rugged
- Advanced trench process technology

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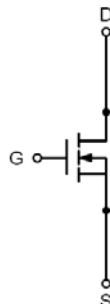
Applications

- Synchronous Rectification
- Power Management in Inverter System

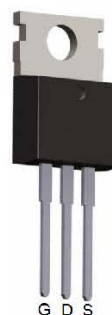
Switching Time Test Circuit and Waveforms



Pin Description



Marking and pin Assignment



TO-220-3L top view

Package Marking and Ordering Information

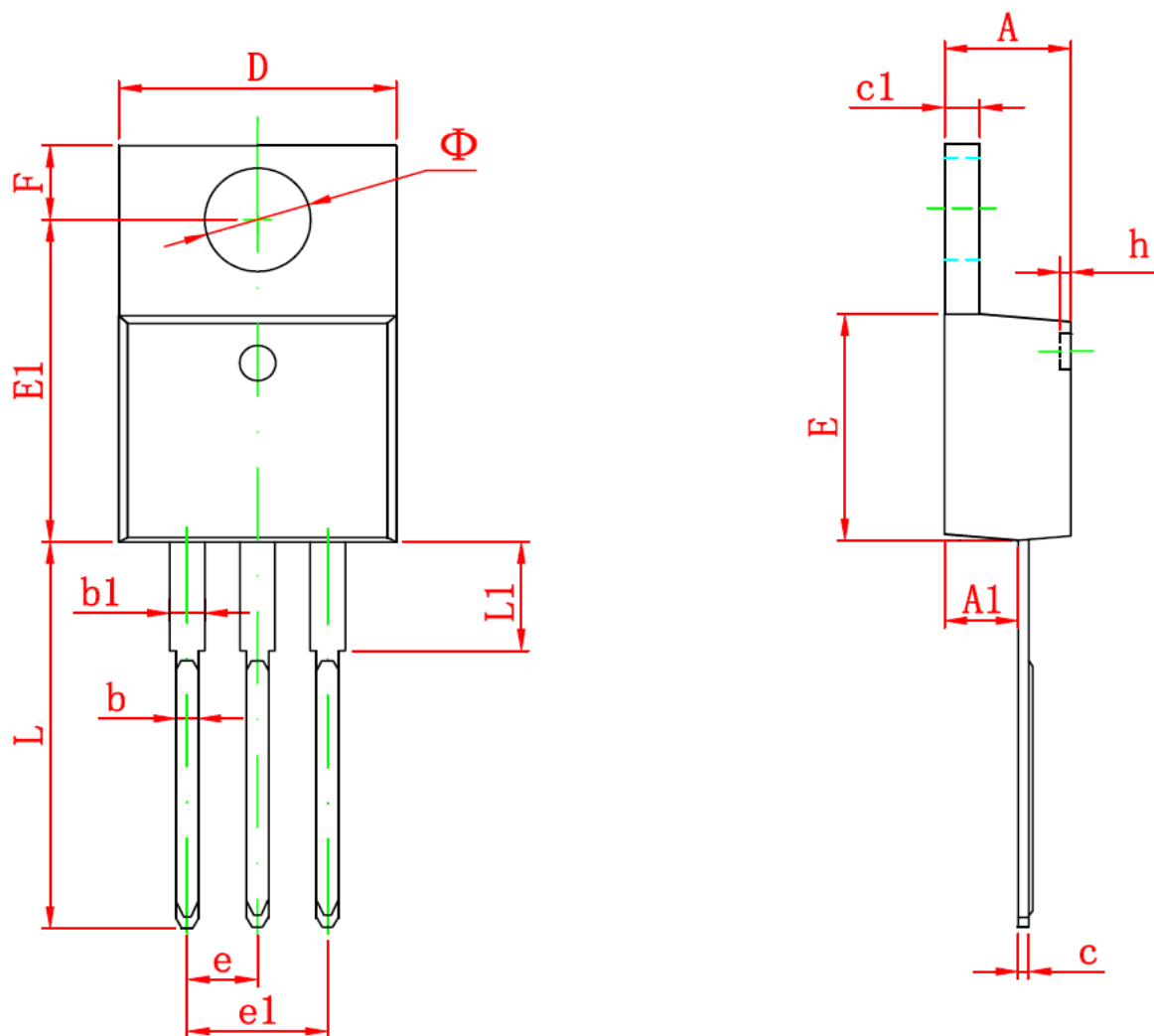
Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
HM741	HM741	TO-220-3L	-	-	-

Key Electrical Characteristics (TO-220 package)

Parameter	Description	Min	Typ	Max	Test condition
BV _{DSS} , V	Drain-to-Source Breakdown Voltage	200	-	-	V _{GS} = 0 V, I _D = 250 μA
I _D , A	Continuous Drain Current	-	-	9*	T _j = 25 °C
R _{DS(on)} , Ohm	Static Drain-to-Source On Resistance	-	0,35	0,4	V _{GS} = 10 V, I _D = 4,5 A
V _{GS(th)} , V	Gate Threshold Voltage	2,0	-	4,0	V _{DS} = V _{GS} , I _D = 250 μA
I _{DSS} , μA	Drain-to-Source Leakage Current	-	-	1,0	V _{DS} = 200 V, V _{GS} = 0 V
I _{GSS} , nA	Gate-to-Source Leakage Current	-	-	±100	V _{GS} = ± 25 V, V _{DS} = 0 V
T _j , T _{STG} , °C	Operating Junction and Storage Temperature Range	- 55 ~ +150			

* Drain current limited by junction temperature

TO-220-3L PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	4.470	4.670	0.176	0.184
A1	2.520	2.820	0.099	0.111
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.310	0.530	0.012	0.021
c1	1.170	1.370	0.046	0.054
D	10.010	10.310	0.394	0.406
E	8.500	8.900	0.335	0.350
E1	12.060	12.460	0.475	0.491
e	2.540 TYP		0.100 TYP	
e1	4.980	5.180	0.196	0.204
F	2.590	2.890	0.102	0.114
h	0.000	0.300	0.000	0.012
L	13.400	13.800	0.528	0.543
L1	3.560	3.960	0.140	0.156
Φ	3.735	3.935	0.147	0.155

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